



FIT

CPU/Memory Module SKT Product & Specifications

Foxconn Interconnect Technology Limited

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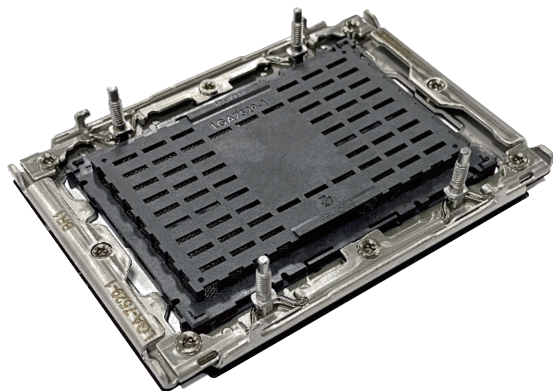
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Product Categories

Intel Socket - BR



Features

- Pin count: 7529
- Pitch: 0.94mm × 0.81mm Hex
- Contact plating: 30u" Au plating
- Socket Outline dimension: 75.5mm × 109.5mm
- Bolster Outline dimension: 140.5mm × 100.7mm × 24.2mm
- BP Outline dimension: 140.5mm × 100.5mm × 10.3mm
- Application: Networking, Server, Storage, Big Data, Cloud, Datacenter, Edge Computing, and HPC

Ampere Socket - 5964



Features

- Pin count: 5964
- Pitch: 1.00mm × 0.87mm Hex
- Contact plating: 30u" Au plating
- Socket Outline dimension: 93.0mm × 76.0mm × 9.5mm
- ILM Outline dimension: 133mm × 94mm × 14.3mm
- BP Outline dimension: 135.5mm × 96mm × 10.15mm
- Application: Networking, Server, Storage, Big Data, Cloud, Datacenter, Edge Computing, and HPC

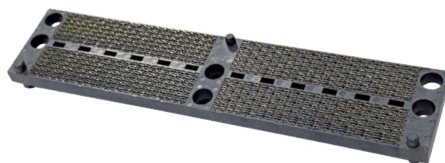
Features

- Pin count: 616
- Pitch: 1.38mm × 1.0mm
- Body Size: 73.9mm × 14.65mm × 2.87mm

Dell CAMM 1.0 Socket



Dell CAMM 2.0 Socket



Features

- Pin count: 356
- Pitch: 1.38mm × 1.0mm
- Body Size: 77.8mm × 17mm × 2.85mm

Features

- Pin count: 644
- Pitch: 1.38mm × 1.0mm
- Body Size: 77.8mm × 17mm × 1mm

Intel CAMM 2.0 Socket



Features

- Pin count: 6096
- Pitch: 0.94mm × 0.81mm Hex
- Contact plating: 30u" Au plating
- Socket Outline dimension: 83mm × 77.9mm
- SRM Outline dimension: 119.3mm × 92.9mm × 10.18mm
- Socket Retention Mechanism (SRM)
- BP Outline dimension: 105.5mm × 92.9mm × 14.4mm
- Application: Networking, Server, Storage, Big Data, Cloud, Datacenter, Edge Computing, and HPC

AMD Socket - SP5

